



In the United States Patent and Trademark Office

In re the Application of  
Lee D. Whetsel

TI-20787.2

Serial No. 09/697,941

Art Unit: 2829

Filed: 10/26/2000

Examiner: Nguyen Vinh P.

Title: Fault Tolerant Selection of Die on Wafer

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**Amendment A Under 37 CFR 1.111**

July 3, 2002

Assistant Commissioner  
For Patents  
Washington, D. C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is  
being deposited with the U.S. Postal Service as  
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Assistant Commissioner For Patents, Washington,  
D.C. 20231 on July 3, 2002.  
*Lawrence J. Bassuk*  
Lawrence J. Bassuk, Reg. No. 29,043

Responsive to the Examiner's Action of February 11, 2002,  
please amend this application as follows:

**In the Title:**

Amend the title to read as follows:

--Integrated Circuit Die With Bypass Bond Pad--

**In the Specification:**

Page 1, before line 1, insert:

--This application is a divisional of Application No. 09/416,562, filed October 12, 1999, now US 6,166,557; which was a divisional of Application No. 08/741,457, filed October 31, 1996,

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01 F01:00 116.10 CH  
02 F01:02 588.00 CH

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2002  
*Lawrence J. Bassuk*  
Lawrence J. Bassuk, Reg. No. 29,043

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Transmitted herewith is an amendment in this application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	32	Minus	20	= 12	x \$18 =	\$ 216
Ind. Claims	10	Minus	3	= 7	x \$84 =	\$ 588
TOTAL ADDITIONAL FEE FOR THIS AMOUNT						\$ 804

Under 37 C.F.R. § 1.16(k) please charge the total additional fee, and  
any further fees, or credit overpayment to Deposit Account No. 20-0668  
of Texas Instruments Incorporated.

Respectfully submitted,

Lawrence J. Bassuk  
Reg. No. 29,043  
Attorney for Applicant

Texas Instruments Incorporated  
P.O. Box 655474, M/S 3999  
Dallas, Texas 75265  
(972) 917-4418